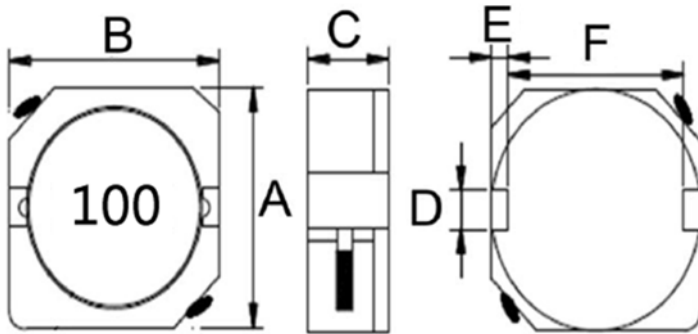


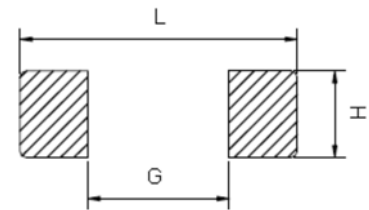
FEATRLRES

- Low profile very effective in space-conscious applications.
- Low resistance and high energy storage.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGLRATIONS & DIMENSIONS (unit in mm)



Recommended Land pattern



Size	A	B	C	D	E	F
HSBR103R	10.2±0.3	10.0±0.3	3.0 max.	3.0±0.1	1.2±0.15	7.7±0.3

L	G	H
10.5	7.3	3.2

ELECTRICAL CHARACTERISTICS

Part Number	Inductance (uH)	Test Frequency (Hz)	DCR (Ω) max.	I sat (A) max.	I rms (A) typ.
HSBR103R-R80Y	0.8±30%	0.1V/100K	0.0057	11.2	8.30
HSBR103R-1R5Y	1.5±30%	0.1V/100K	0.011	8.00	5.80
HSBR103R-2R2Y	2.2±30%	0.1V/100K	0.0169	6.70	5.10
HSBR103R-3R3Y	3.3±30%	0.1V/100K	0.021	5.56	4.70
HSBR103R-4R7Y	4.7±30%	0.1V/100K	0.030	4.65	4.00
HSBR103R-6R8Y	6.8±30%	0.1V/100K	0.035	3.84	3.60
HSBR103R-8R2Y	8.2±30%	0.1V/100K	0.050	3.54	3.00
HSBR103R-100M	10±20%	0.1V/100K	0.059	3.18	2.80
HSBR103R-150M	15±20%	0.1V/100K	0.091	2.60	2.05
HSBR103R-220M	22±20%	0.1V/100K	0.143	2.16	1.60
HSBR103R-330M	33±20%	0.1V/100K	0.202	1.74	1.35
HSBR103R-470M	47±20%	0.1V/100K	0.299	1.43	1.20
HSBR103R-560M	56±20%	0.1V/100K	0.325	1.36	1.15
HSBR103R-680M	68±20%	0.1V/100K	0.429	1.22	0.95
HSBR103R-820M	82±20%	0.1V/100K	0.494	1.14	0.80
HSBR103R-101M	100±20%	0.1V/100K	0.683	1.02	0.70

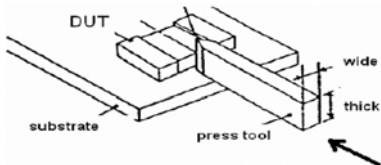
HSBR103R-121M	120±20%	0.1V/100K	0.754	0.89	0.65
HSBR103R-151M	150±20%	0.1V/100K	0.871	0.84	0.51

Note:

Based on inductance change ($\Delta L/L_0 : \leq -35\%$) @ ambient temp. 25°C Based on temperature rise ($\Delta T : 40^\circ\text{C typ.}$)

Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	1. -10~+40°C, 50~60%RH (Product with taping) 2. -40~+125°C (on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately $\Delta L 30\%$	Saturation DC Current (Isat) will cause L0 to drop $\Delta L(\%)$
Heat Rated Current (Irms)	Approximately $\Delta T 40^\circ\text{C}$	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T(^\circ\text{C})$. 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : 125±2°C (Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity : 85±2 * R.H, Temperature : 85°C ±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) 1. Baked at 50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1 : -40±2°C 30±5min Step2 : 25±2°C ≤0.5min Step3 : 125±2°C 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 1.52mm ±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: ≥0805 inch(2012mm): 40x100x1.2mm <0805 inch(2012mm): 40x100x0.8mm Bending depth: ≥0805 inch(2012mm): 1.2mm <0805 inch(2012mm): 0.8mm duration of 10 sec.

Shock	Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<table><tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150℃,60sec.. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5℃ Flux for lead free: Rosin. 9.5% Dip time: 4±1sec Depth: completely cover the termination															
Resistance to Soldering Heat		Depth: completely cover the termination <table><tr><th>Temperature(℃)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table>	Temperature(℃)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
Temperature(℃)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles														
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1														
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 															

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.